



Material Content Data Sheet



Sales Product Name				SAL-TC233LP-32F200N AC		Issued		19. January 2018	
MA#				MA001677706					
Package				PG-TQFP-100-23		Weight*		698.65 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	23.351	3.34	3.34	33423	33423	
leadframe	inorganic material	phosphorus	7723-14-0	0.056	0.01		80		
	non noble metal	zinc	7440-66-6	0.223	0.03		319		
	non noble metal	iron	7439-89-6	4.458	0.64		6381		
wire	non noble metal	copper	7440-50-8	181.029	25.91	26.59	259112	265892	
	noble metal	gold	7440-57-5	0.002	0.00		2		
	noble metal	palladium	7440-05-3	0.033	0.00		47		
encapsulation	non noble metal	copper	7440-50-8	1.466	0.21	0.21	2098	2147	
	organic material	carbon black	1333-86-4	1.408	0.20		2015		
	plastics	epoxy resin	-	59.588	8.53		85290		
leadfinish	inorganic material	silicondioxide	60676-86-0	408.203	58.45	67.18	584270	671575	
	noble metal	palladium	7440-05-3	0.003	0.00		4		
	noble metal	silver	7440-22-4	0.003	0.00		4		
plating	noble metal	gold	7440-57-5	0.005	0.00		7		
	non noble metal	nickel	7440-02-0	4.642	0.66	0.66	6645	6660	
	noble metal	silver	7440-22-4	0.005	0.00		7		
glue	noble metal	palladium	7440-05-3	0.005	0.00		8		
	noble metal	gold	7440-57-5	0.009	0.00		12		
	non noble metal	nickel	7440-02-0	8.662	1.24	1.24	12399	12426	
*deviation	plastics	epoxy resin	-	1.211	0.17		1733		
	noble metal	silver	7440-22-4	4.292	0.61	0.78	6144	7877	
						Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com